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Field device integration (FDI®) – Part 5: FDI Information Model

INTERNATIONAL
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FIELD DEVICE INTEGRATION (FDI®) –

Part 5: FDI® Information Model

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IEC 62769-5 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation. It is an International Standard.

This third edition cancels and replaces the second edition published in 2021. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

a) added INTERACTIVE_TRANSFER_TO_DEVICE ACTION.

The text of this International Standard is based on the following documents:

Draft	Report on voting
65E/858/CDV	65E/915/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

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INTRODUCTION

The IEC 62769 series has the general title *Field Device Integration (FDI)* and the following parts:

- Part 1: Overview
- Part 2: FDI Client
- Part 3: FDI Server
- Part 4: FDI Packages
- Part 5: FDI Information Model
- Part 6: FDI Technology Mapping
- Part 7: FDI Communication Devices
- Part 100: Profiles – Generic Protocol Extensions
- Part 101-1: Profiles – Foundation Fieldbus H1
- Part 101-2: Profiles – Foundation Fieldbus HSE
- Part 103-1: Profiles – PROFIBUS
- Part 103-4: Profiles – PROFINET
- Part 109-1: Profiles – HART and WirelessHART
- Part 115-2: Profiles – Protocol-specific Definitions for Modbus RTU
- Part 150-1: Profiles – ISA 100.11a

FIELD DEVICE INTEGRATION (FDI®) –

Part 5: FDI® Information Model

1 Scope

This part of IEC 62769 defines the FDI®[1] Information Model. One of the main tasks of the Information Model is to reflect the topology of the automation system. Therefore, it represents the devices of the automation system as well as the connecting communication networks including their properties, relationships, and the operations that can be performed on them. The types in the AddressSpace of the FDI® Server constitute ~~a~~ some kind of catalogue, which is built from FDI® Packages.

The fundamental types for the FDI® Information Model are well defined in OPC UA for Devices (IEC 62541-100). The FDI® Information Model specifies extensions for a few special cases and otherwise explains how these types are used and how the contents are built from elements of DevicePackages.

The overall FDI® architecture is illustrated in Figure 1. The architectural components that are within the scope of this document have been highlighted in this illustration.

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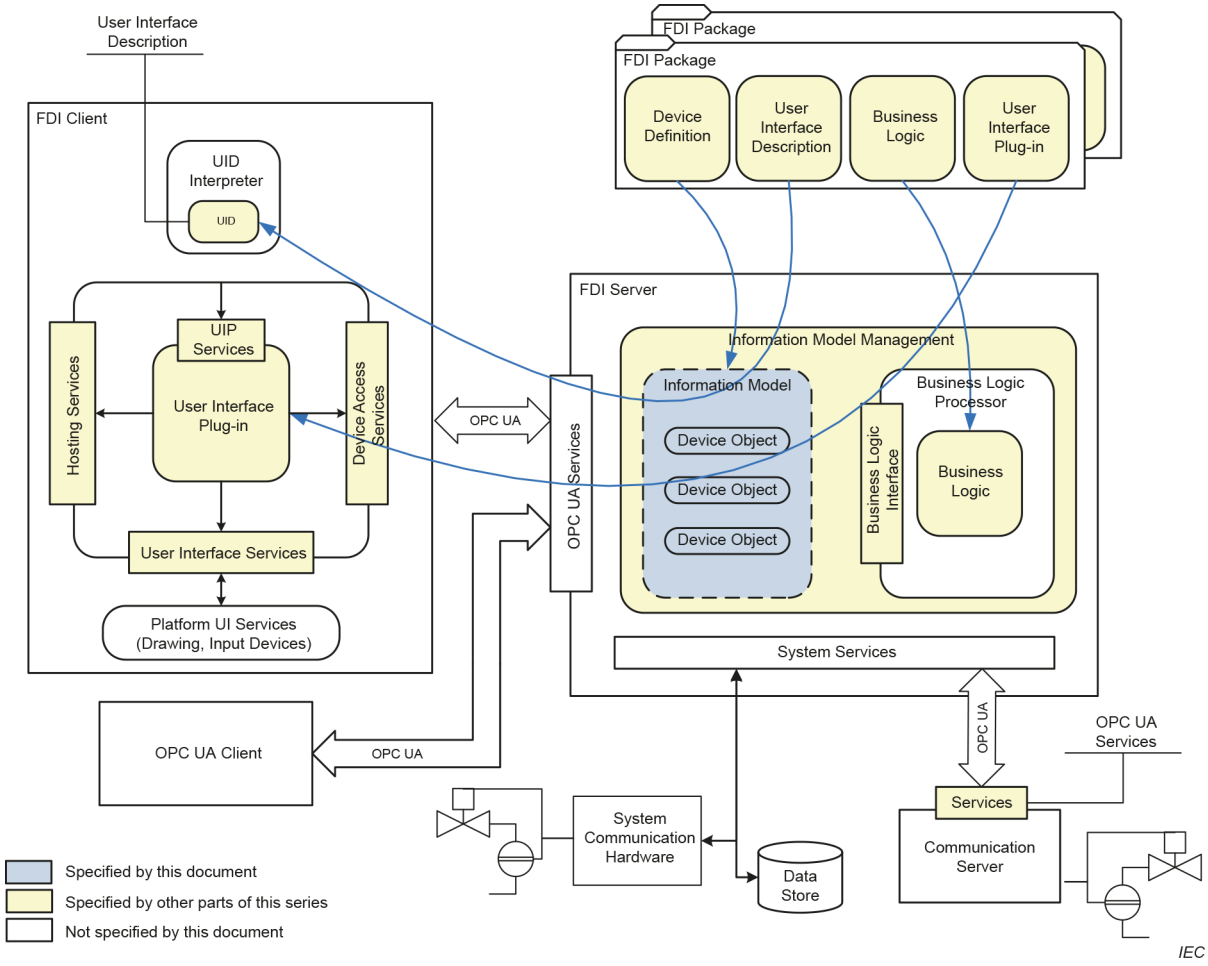

Figure 1 – FDI® architecture diagram

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

~~IEC 61784-1, *Industrial communication networks – Profiles – Part 1: Fieldbus profiles*~~

IEC 61784-1-3:2023, *Industrial networks – Profiles – Part 1-3: Fieldbus profiles – Communication Profile Family 3*

IEC 61804-3, *Devices and integration in enterprise systems – Function blocks (FB) for process control and electronic device description language (EDDL) – Part 3: EDDL syntax and semantics*

IEC 61804-4, *Devices and integration in enterprise systems – Function blocks (FB) for process control and electronic device description language (EDDL) – Part 4: EDD interpretation*

IEC 62541-3, *OPC Unified Architecture – Part 3: Address Space Model*

IEC 62541-4, *OPC Unified Architecture – Part 4: Services*

IEC 62541-5, *OPC Unified Architecture – Part 5: Information Model*

IEC 62541-6, *OPC Unified Architecture – Part 6: Mappings*

IEC 62541-8, *OPC Unified Architecture – Part 8: Data Access*

IEC 62541-100, *OPC Unified Architecture – Part 100: ~~OPC UA for Devices~~ Device Interface*

IEC 62769-1, *Field Device Integration (FDI®) – Part 1: Overview*

IEC 62769-2, *Field Device Integration (FDI®) – Part 2: ~~FDI~~ Client*

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IEC 62769-6, *Field Device Integration (FDI®) – Part 6: FDI® Technology Mappings*

IEC 62769-7, *Field Device Integration (FDI®) – Part 7: ~~FDI~~ Communication Devices*

IEC 62769-1xx (all parts), *Field Device Integration (FDI®) – Part 1xx-y: Profiles*

OPC 10000-19, *OPC Unified Architecture – Part 19: Dictionary Reference*

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Edition 3.0 2023-04

INTERNATIONAL STANDARD

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Field device integration (FDI®) – Part 5: FDI Information Model

Intégration des appareils de terrain (FDI®) – Partie 5: Modèle d'Information FDI

IEC 62769-5:2023-04(en-fr)

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Part 5: FDI® Information Model

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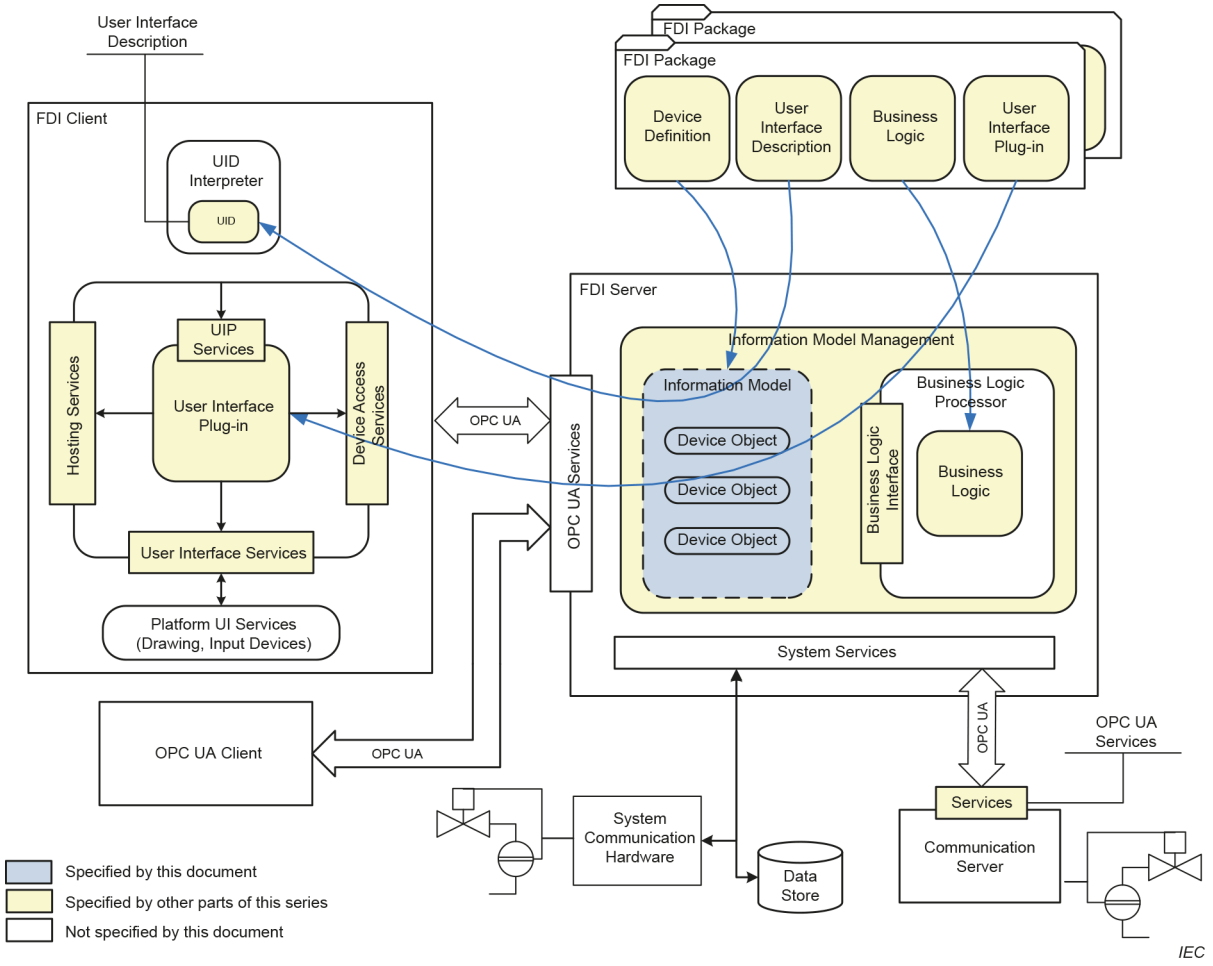

Figure 1 – FDI® architecture diagram

2 Normative references

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IEC 62769-1xx (all parts), *Field Device Integration (FDI®) – Part 1xx-y: Profiles*

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INTÉGRATION DES APPAREILS DE TERRAIN (FDI®) –

Partie 5: Modèle d'Information FDI®

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Cette troisième édition annule et remplace la deuxième édition parue en 2021. Cette édition constitue une révision technique.

Cette édition inclut les modifications techniques majeures suivantes par rapport à l'édition précédente:

a) ajout d'INTERACTIVE_TRANSFER_TO_DEVICE ACTION.

Le texte de cette Norme internationale est issu des documents suivants:

Projet	Rapport de vote
65E/858/CDV	65E/915/RVC

Le rapport de vote indiqué dans le tableau ci-dessus donne toute information sur le vote ayant abouti à son approbation.

La langue employée pour l'élaboration de cette Norme internationale est l'anglais.

Ce document a été rédigé selon les Directives ISO/IEC, Partie 2, il a été développé selon les Directives ISO/IEC, Partie 1 et les Directives ISO/IEC, Supplément IEC, disponibles sous www.iec.ch/members_experts/refdocs. Les principaux types de documents développés par l'IEC sont décrits plus en détail sous www.iec.ch/publications.

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INTÉGRATION DES APPAREILS DE TERRAIN (FDI®) –

Partie 5: Modèle d'Information FDI®

1 Domaine d'application

La présente partie de l'IEC 62769 définit le Modèle d'Information FDI®[1]. L'un des principaux objectifs du Modèle d'Information est de refléter la topologie du système d'automatisation. Par conséquent, il représente les appareils du système d'automatisation ainsi que les réseaux de communication connectés, y compris leurs propriétés, leurs relations et les opérations dont ils peuvent faire l'objet. Les types présents dans l'AddressSpace du Serveur FDI® constituent un catalogue, qui est créé à partir des Paquetages FDI®.

Les types fondamentaux pour le Modèle d'Information FDI® sont définis dans l'OPC UA pour les Appareils (IEC 62541-100). Le Modèle d'Information FDI® spécifie des extensions pour quelques cas spéciaux et explique la façon dont ces types sont utilisés et dont les contenus sont construits à partir des éléments de DevicePackages.

L'architecture FDI® complète est représentée à la Figure 1. Les composants architecturaux qui relèvent du domaine d'application du présent document ont été mis en évidence dans cette représentation.

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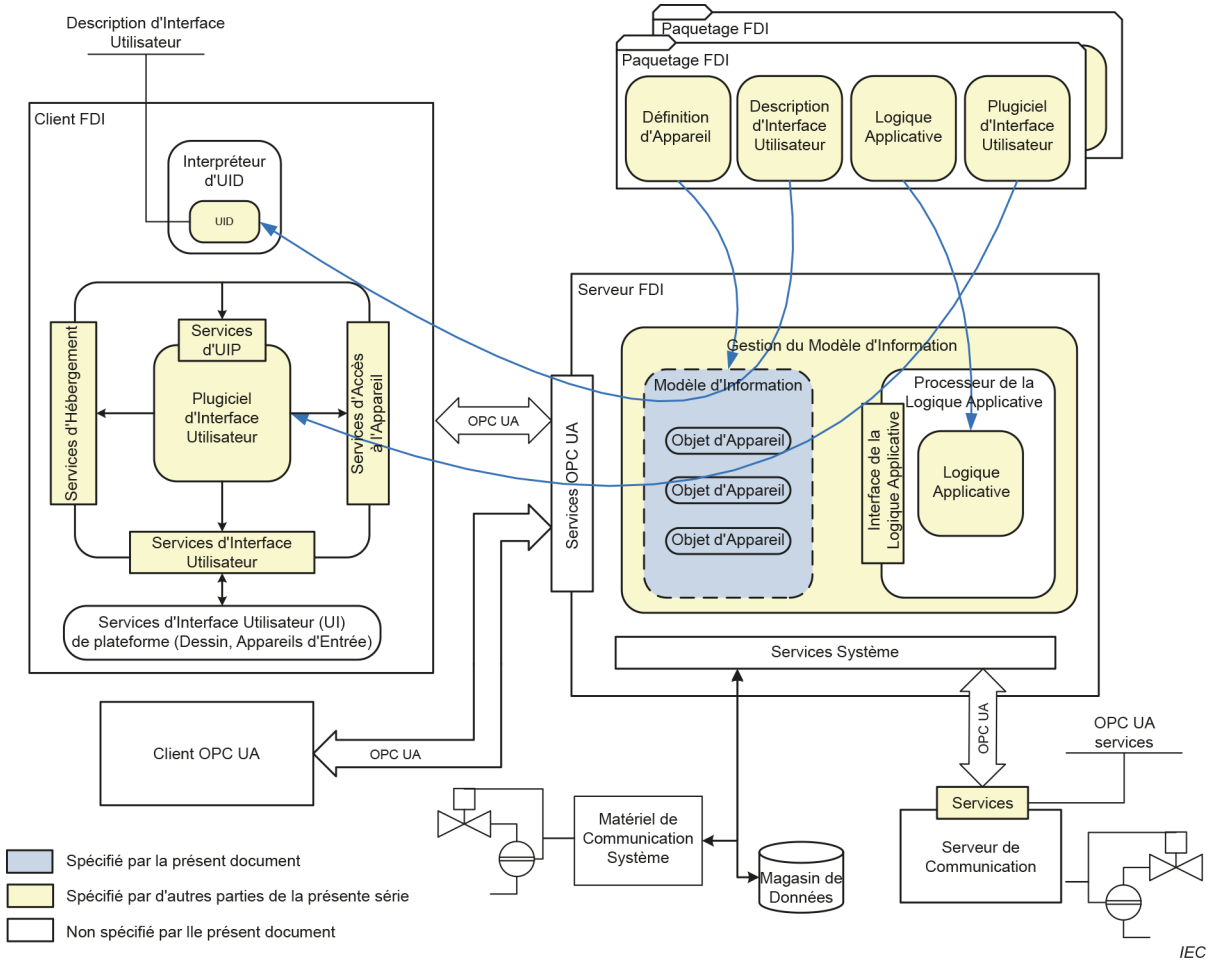

Figure 1 – Diagramme de l'architecture FDI®

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IEC 61784-1-3:2023, *Réseaux industriels – Profils – Partie 1-3: Profils de bus de terrain – Famille de profils de communication 3*

IEC 61804-3, *Les dispositifs et leur intégration dans les systèmes de l'entreprise – Blocs fonctionnels (FB) pour les procédés industriels et le langage de description électronique de produits (EDDL) – Partie 3: Sémantique et syntaxe EDDL*

IEC 61804-4, *Les dispositifs et leur intégration dans les systèmes de l'entreprise – Blocs fonctionnels (FB) pour les procédés industriels et le langage de description électronique de produits (EDDL) – Partie 4: Interprétation EDD*

IEC 62541-3, *Architecture unifiée OPC – Partie 3: Modèle d'espace d'adressage*

IEC 62541-4, *Architecture unifiée OPC – Partie 4: Services*

IEC 62541-5, *Architecture unifiée OPC – Partie 5: Modèle d'information*

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IEC 62769-1, *Intégration des appareils de terrain (FDI®) – Partie 1: Vue d'ensemble*

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IEC 62769-1xx (toutes les parties), *Intégration des appareils de terrain (FDI®) – Partie 1xx-y: Profils*

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